



Material Composition Declaration

EPC2302

Company Name	Efficient Power Conversion (EPC)	Issue Date:	1/8/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	31.3 mg	Type of Product:	eGaN FET in FCQFN package

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	9.8134	31.3971	33.3494	313971
	Silicon oxide	7631-86-9	0.0907	0.2902		2902
	Silicon nitride	12033-89-5	0.0300	0.0959		959
	Gallium nitride	25617-97-4	0.0659	0.2110		2110
	Aluminum	7429-90-5	0.1317	0.4214		4214
	Aluminum nitride	24304-00-5	0.0140	0.0448		448
	Titanium	7440-32-6	0.0026	0.0084		84
	Titanium nitride	25583-20-4	0.1258	0.4024		4024
	Copper	7440-50-8	0.0022	0.0070		70
	Tungsten	7440-33-7	0.0095	0.0303		303
	Polyimide		0.1378	0.4409	4409	
Under Bump Metal	Titanium	7440-32-6	0.0010	0.0031	0.0340	31
	Copper	7440-50-8	0.0097	0.0309		309
Solder Bump	Copper	7440-50-8	0.8115	2.5963	3.5475	25963
	Nickel	7440-02-0	0.0576	0.1844		1844
	Tin	7440-31-5	0.2354	0.7530		7530
	Silver	7440-22-4	0.0043	0.0138		138
Package	Copper	7440-50-8	11.7262	37.5168	63.0691	375168
	Iron	7439-89-6	0.3007	0.9620		9620
	Mold Compound		7.0000	22.3958		223958
	Tin	7440-31-5	0.6859	2.1945		21945
Sum in total:			31.2559	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.